

## PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT5645683

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
MICHAEL A. SMITH	07/31/2019
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	MICRON TECHNOLOGY, INC.
<b>Street Address:</b>	8000 SOUTH FEDERAL WAY
<b>Internal Address:</b>	MS 525
<b>City:</b>	BOISE
<b>State/Country:</b>	IDAHO
<b>Postal Code:</b>	83716
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	16527552
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(612)573-2005
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<b>Address Line 4:</b>	MINNEAPOLIS, MINNESOTA 55402
<b>ATTORNEY DOCKET NUMBER:</b>	M3401.176.101
<b>NAME OF SUBMITTER:</b>	THOMAS W. LEFFERT
<b>SIGNATURE:</b>	/Thomas W. Leffert/
<b>DATE SIGNED:</b>	07/31/2019
<b>Total Attachments: 2</b>	
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source=2019-07-31-Assignment#page2.tif	

## ASSIGNMENT

WHEREAS, we:

**Michael A. Smith, residing at 8924 W. Dulcimer, Boise, Idaho 83709.**

made certain new and useful inventions and improvements for which we executed an application for Letters Patent of the United States herewith, and which is entitled ISOLATION STRUCTURES FOR INTEGRATED CIRCUIT DEVICES.

AND WHEREAS, Micron Technology, Inc., a corporation organized and existing under and by virtue of the laws of the State of Delaware, and having an office and place of business at 8000 South Federal Way, MS 525, Boise, Idaho, 83716, (hereinafter "Assignee") is desirous of acquiring the entire right, title and interest in and to said inventions, improvements and application and in and to the Letters Patent to be obtained therefor;

NOW, THEREFORE, to all whom it may concern, be it known that for good and valuable consideration, the receipt and sufficiency whereof is hereby acknowledged, we have sold, assigned, and transferred, and by these presents do sell, assign and transfer unto said Assignee, its successors or assigns, the entire right, title and interest for all countries in and to all inventions and improvements disclosed in the aforesaid application, and in and to the said application, all divisions, continuations, continuations-in-part, or renewals thereof, all Letters Patent which may be granted therefrom, and all reissues or extensions of such patents, and in and to any and all applications which have been or shall be filed in any foreign countries for Letters Patent on the said inventions and improvements, including an assignment of all rights under the provisions of the International Convention, and all Letters Patent of foreign countries which may be granted therefrom; and we do hereby authorize and request the Commissioner of Patents and Trademarks to issue any and all United States Letters Patent for the aforesaid inventions and improvements to the said Assignee as the assignee of the entire right, title and interest in and to the same, for the use of the said Assignee, its successors and assigns.

AND, for the consideration aforesaid, we do hereby agree that we and our respective executors and legal representatives will make, execute and deliver any and all other instruments in writing including any and all further application papers, affidavits, assignments and other documents, and will communicate to said Assignee, its successors and representatives all facts known to us relating to said improvements and the history thereof and will testify in all legal proceedings and generally do all things which may be necessary or desirable more effectually to secure to and vest in said Assignee, its successors or assigns the entire right, title and interest in and to the said improvements, inventions, applications, Letters Patent, rights, titles, benefits, privileges and advantages hereby sold, assigned and conveyed, or intended so to be.

AND, furthermore we covenant and agree with said Assignee, its successors and assigns, that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by me/us and that full right to convey the same as herein expressed is possessed by us.

Docket No.: M3401.176.101  
Serial No.: Unknown  
Title: ISOLATION STRUCTURES FOR INTEGRATED CIRCUIT DEVICES

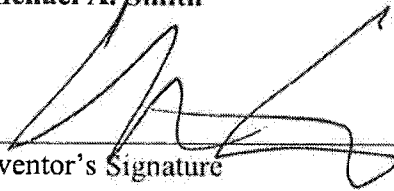
Micron Docket: 2018-0691.00/US  
Filing Date: Herewith  
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In witness whereof, executed by the undersigned on the date opposite the undersigned name.

Full Name of Inventor: **Michael A. Smith**

7-31-19

Date



Inventor's Signature